| g GE Energy | **Functional Testing Specification** |
|---|---|
| ***Parts & Repair Services***<br>***Louisville, KY*** | **CAN-GEB-471L0217** |

## Test Procedure for a card

**DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column**

| REV. | DESCRIPTION | SIGNATURE | REV. DATE |
|---|---|---|---|
| A | Transition Canadian work instruction to local format | G. Chandler | 2/8/2013 |
| B | | | |
| C | | | |



| PREPARED BY | REVIEWED BY | REVIEWED BY | QUALITY APPROVAL |
|---|---|---|---|
| G. Chandler | | | Charlie Wade |
| **DATE** | **DATE** | **DATE** | **DATE** |
| 2/8/2013 | | | 2/8/2013 |

## 1. SCOPE

**1.1** This is a functional testing procedure for a Card.

## 2. STANDARDS OF QUALITY

**2.1** Refer to the current revision of the IPC-A-610 standard for workmanship standards.

## 3. APPLICABLE DOCUMENTS

**3.1** The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
**3.1.1** Check board's electronic folder for more information

## 4. ENGINEERING REQUIREMENTS

**4.1** Equipment Cleaning
**4.1.1** Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.
**4.2** Equipment Inspection
**4.2.1** Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
**4.2.1.1** Wires - broken, cracked, or loosely connected
**4.2.1.2** Terminal strips / connectors - broken or cracked
**4.2.1.3** Components - visually damaged
**4.2.1.4** Capacitors - bloated or leaking
**4.2.1.5** Solder joints - damaged or cold
**4.2.1.6** Circuit board - burned or de-laminated
**4.2.1.7** Printed wire runs / Traces - burned or damaged

## 5. EQUIPMENT REQUIRED

**5.1** The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

| Qty | Reference # | Description |
|---|---|---|
| 1 | | Fluke 87 DMM (or Equivalent) |
| 1 | | +12VDC Power Supply |
| 1 | | +5.3VDC Power Supply |
| | | |
| | | |

**6. Modifications/Upgrades**

**6.1** Fill out if applicable.

**7. Testing Process**

**7.1 Testing Procedure**

**7.1.1** This card consists of 16 identical logic circuits. Use the following procedure to test all 16 independently.

**7.1.2** Apply +12VDC to pin 27, com to pin1

**7.1.3** Apply +5.3VDC to pin 28, com to pin 1

**7.1.4** First, momentarily apply +5.3VDC to pin 49 (MR) to reset all circuits.

**7.1.5** Using the chart momentarily apply +5.3VDC to “S”.

**7.1.6** Verify LED lights and “OL” goes low and stays that way.

**7.1.7** Momentarily apply +5.3VDC to “MR” and verify LED goes off and “OL” returns to a high.

***7.2 ***TEST COMPLETE ******

**8. Notes**

**8.1** None at this time.

**9. Attachments**

**9.1** See next page for circuit information, attachment 1.

Attachment 1